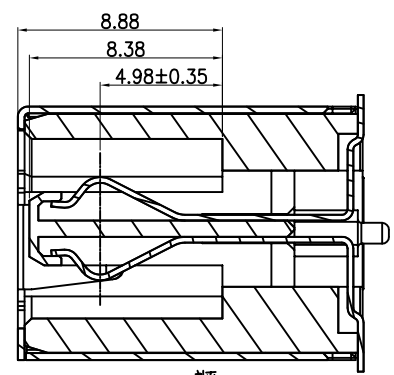
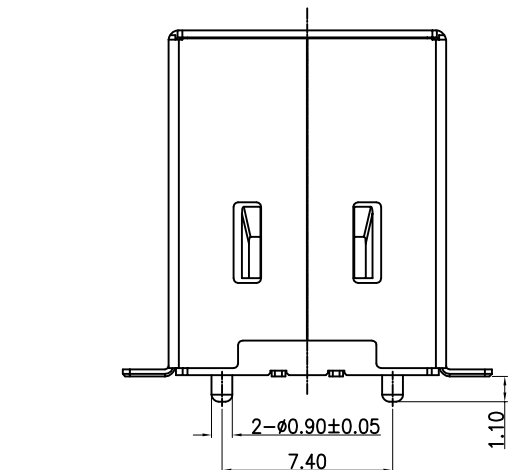
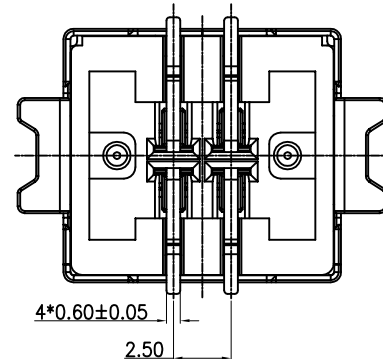
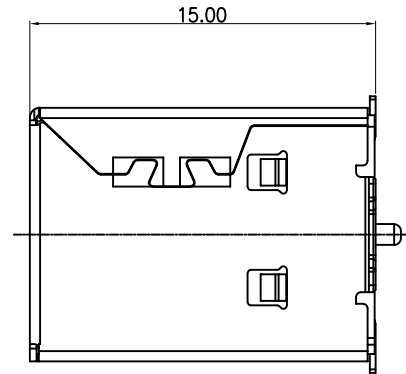
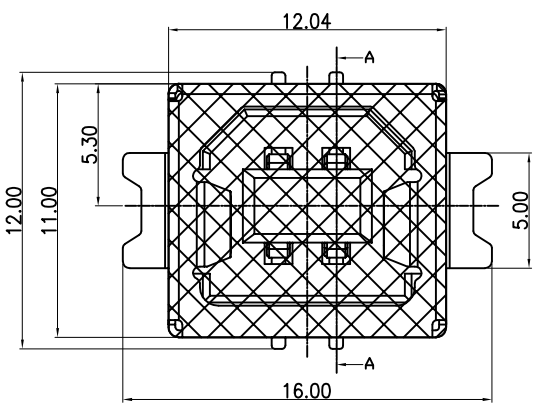


RECOMMENDED PCB LAYOUT(TOP VIEW)
GENERAL TOLERANCES:± 0.05



修订 REV NO	标记 MARK	修改摘要 REVISION DESCRIPTION	签名 SIGNATURE	日期 DATE
		NEW DWG		2016-03-12

NOTE:

- Material:
Housing: LCP, Black (Halogen free); Thermoplastics, UL94V-0;
Contact: Copper Alloy
Shell: Copper Alloy
- FINISH:
Contact: Gold Flash Plated on Contact Area,
80u" Tin Bright Plated on Solder Tails,
50u" Min. Nickel Underplating Over All.
Shell: 50u" Min. Nickel Underplating Over All.
- Specification:
3.1: Voltage Current Rating: 1.5Amp. 30V/AC
3.2: Electrical:
Insulation Resistance: 100MΩ Min.
Contact Resistance: 20mΩ Max.
Dielectric Withstanding Voltage: 500V/AC 1Minute
3.3: MECHANICAL
Mating force: 35N Max.
Unmating force: 10N Min.
Durability: 1500 cycles Min.

4	Mylar	Mylar	高温唛啦 (W12.0*TO.06mm)	
3	胶芯	LCP	黑色LCP, 无卤	
2	外壳	C2680	铜壳镀镍50u" Min.	
1	端子	C5191	镀半金亮锡G/F	
项次 NO.	品称 NAME	名称 P/N	表面处理 PLATING	备注 REMARK



深圳市华德共创科技有限公司
Shenzhen Huade co-create Technology Co., LTD
电话: 0755-27111216 传真: 0755-29940187

-TOLERANCES- UNLESS OTHERWISE SPECIFIED 公差参数表		TITLE: USB 2.0 BF直立式 (H=15MM) SMT贴片 产品名称: 式 贴唛啦	
X.X ±0.30	X.X* ±3°	APPD: 核准:	PART NO: 产品编号: USB BF-GD-104PWB
X.XX ±0.20	X.XX* ±2°	CHECK: 校对: 王建业	DATE SCALE UNIT CODE NUMBER
X.XXX ±0.10	X.XXX* ±1°	DRAW: 绘图: 黄艳兰	2016-03-12 1:1 mm A001